



Material Content Data Sheet



Sales Product Name				IPB036N12N3 G		Issued		26. September 2017	
MA#				MA000918620					
Package				PG-TO263-7-3		Weight*		1532.79 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	17.914	1.17	1.17	11687	11687	
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		524		
	inorganic material	phosphorus	7723-14-0	0.241	0.02		157		
	non noble metal	copper	7440-50-8	801.714	52.30	52.37	523043	523724	
wire	non noble metal	aluminium	7429-90-5	19.664	1.28	1.28	12829	12829	
encapsulation	organic material	carbon black	1333-86-4	8.447	0.55		5511		
	plastics	epoxy resin	-	92.914	6.06		60618		
	inorganic material	silicondioxide	60676-86-0	461.757	30.13	36.74	301252	367381	
leadfinish	non noble metal	tin	7440-31-5	12.317	0.80	0.80	8035	8035	
plating	non noble metal	nickel	7440-02-0	0.269	0.02		176		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	0	176	
solder	noble metal	silver	7440-22-4	0.260	0.02		170		
	non noble metal	tin	7440-31-5	0.208	0.01		136		
	non noble metal	lead	7439-92-1	9.933	0.65	0.68	6480	6786	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		21		
	non noble metal	iron	7439-89-6	0.106	0.01		69		
	non noble metal	copper	7440-50-8	106.210	6.93	6.94	69292	69382	
*deviation	< 10%					Sum in total:	100.00	1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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